

NOTES:

MATERIAL:

1.1 HOUSING: LCP,UL94V-0

1.2 CONTACT: COPPER ALLOY

1.3 SHELL: COPPER ALLOY

Finish:

2.1 Contact: Plated Gold in Mating Area ;

Gold Plated on Solder Balls

Nickel under plated overall

2.2 Shell: Nickel or Tin under Plated surface layer

3.SPECIFICATION:

3.1 CURRENT RATING: 1.0 A

3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 V(ac) FOR 1min

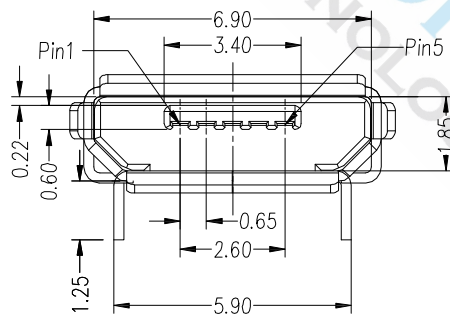
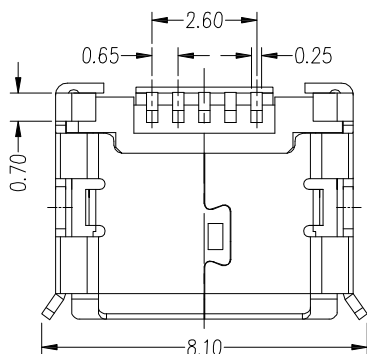
3.3 CONTACT RESISTANCE: 50 mΩ MAX.

3.4 INSULATION RESISTANCE: 100 MΩ MIN.

3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.

3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.

3.7 TEMPERATURE RANGE: -30°C ~ +80°C



DIMENSIONS TOLERANCE METRIC .0=±0.30 .00=±0.20 .000=±0.10 ANG.=±2°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審校(CH'K)	Calvin	圖名(NAME) MICRO USB B TYPE 5P Female SHELL DIP	WISCONN Technology Co., Ltd Tel:02-2790-1979 Fax:02-2790-1569									
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena							料號(PART NUMBER)	WMRU2-05FLBDSR			
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期 DATE)	AUG.10.2017	圖號(DRAW NUMBER)	T002	圖檔(FILE NAME .DWG)		比例(SCALE)	1/1	圖紙(SIZE)	A4	頁次(SHEET)	1	版次(REV.)